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PATENT

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## CLAIMS LISTING

1. (presently amended) An improved light emitting diode mount comprising:  
a light emitting diode die,  
a substrate, ~~[[and]]~~  
a pedestal on the substrate and having a first surface with an area smaller than an area of a first surface of the die, and  
adhesive material affixing the first surface of the die to the first surface of the pedestal, the adhesive material covering and extending beyond the first surface of the pedestal ~~[[smaller than the die connecting the die to the substrate]]~~.
2. (canceled)
3. (original) The device of Claim 1 where the pedestal is formed as part of the substrate.
4. (original) The device of Claim 1 where the pedestal is a separate component from the substrate and the die.
5. (presently amended) The method of mounting a light emitting diode die to a substrate comprising:  
~~[[Forming]]~~ forming a pedestal smaller than the die on one surface of the die, and  
affixing a contact surface of the pedestal to the substrate with adhesive that extends beyond the contact surface of the pedestal.
6. (presently amended) The method of mounting a light emitting diode die to a substrate comprising:  
~~[[Forming]]~~ forming a pedestal smaller than the die on the substrate, and  
affixing a contact surface of the die to a contact surface of the pedestal with adhesive that extends beyond the contact surface of the pedestal.
7. (canceled).
8. (canceled)
9. (new) An improved light emitting diode mount comprising:  
a light emitting diode die,  
a pedestal carried by the die, the pedestal having a smaller profile than the die,  
a substrate, and  
adhesive material affixing a contact surface of the pedestal to the substrate, the adhesive material covering and extending beyond the contact surface of the pedestal.
10. (new) The method of claim 5 wherein forming a pedestal on a surface of a die comprises attaching the pedestal to the die.
11. (new) The method of claim 5 wherein forming a pedestal on a surface of a die comprises forming the pedestal integrally with the die.

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12. (new) The method of claim 6 wherein forming a pedestal on the substrate comprises attaching the pedestal to the substrate.
13. (new) The method of claim 6 wherein forming a pedestal on the substrate comprises forming the pedestal integrally with the substrate.